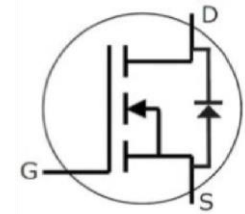


# CPM2-1200-0025A

## Wolfspeed SiC Gen 2 MOSFET

### Description

This is the Wolfspeed's 2nd generation of high performance silicon carbide MOSFET in a packageless bare die format to be implemented into any custom module design. The high blocking voltage with low on-resistance, high speed switching with low capacitance make this MOSFET ideal for high frequency switching application including solar inverters and EV chargers.



Package Types: Bare Die  
PN's: CPM2-1200-0025A

### Features

- Enhanced 2nd Generation SiC MOSFET
- High blocking voltage with low on-resistance
- High speed switching with low capacitance
- Fast intrinsic diode with low reverse recovery

### Applications

- EV Chargers
- SMPS
- Solar Inverters
- Motor Drives
- DC/DC Converters

### Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage, across $T_{vj}$	$V_{DS(max)}$	1200	V
Maximum Gate-Source Voltage, Peak Transient Capability	$V_{GS(max)}$	-10/+25	V
Continuous Drain Current, $V_{GS} = 15V$ , assumes die packaged in TO-247 package with $R_{th(j-c)} < 0.35$ K/W	$I_D$	$T_c = 25^\circ C$	81
		$T_c = 100^\circ C$	60
Pulsed Drain Current, $t_p$ limited by $T_{vj(max)}$	$I_{D(pulse)}$	200	A
Virtual Junction and Storage Temperature	$T_{VJ}, T_{stg}$	-55 to +175	$^\circ C$
Maximum Processing Temperature, in non-reactive ambient	$T_{proc}$	325	$^\circ C$

### Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Recommended Operating Gate - Source Voltage	$V_{GS(op)}$	-5/+20	V

**Electrical Characteristics (T<sub>VJ</sub> = 25 °C)**

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	1200			V	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 100 μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	2	2.9	4	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>DS</sub> = 15 mA
			2.4		V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>DS</sub> = 15 mA, T <sub>VJ</sub> = 175°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		1	100	μA	V <sub>DS</sub> = 1200 V, V <sub>GS</sub> = 0 V
Gate-Source Leakage Current	I <sub>GSS</sub>			250	nA	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>		25	34	mΩ	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 50 A
			43			V <sub>GS</sub> = 20 V, I <sub>D</sub> = 50 A, T <sub>VJ</sub> = 175°C
Transconductance	g <sub>fs</sub>		27.5		S	V <sub>DS</sub> = 20 V, I <sub>DS</sub> = 50 A
			24.6			V <sub>DS</sub> = 20 V, I <sub>DS</sub> = 50 A, T <sub>VJ</sub> = 175°C
Input Capacitance	C <sub>iss</sub>		3350		pF	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 1000 V f = 1 Mhz V <sub>AC</sub> = 25 mV
Output Capacitance	C <sub>oss</sub>		235			
Reverse Transfer Capacitance	C <sub>rss</sub>		24			
C <sub>oss</sub> Stored Energy	E <sub>oss</sub>		126		μJ	V <sub>DS</sub> = 1000 V, f = 1 Mhz
Internal Gate Resistance	R <sub>G(int)</sub>		1.26		Ω	f = 1 Mhz
Gate to Source Charge	Q <sub>gs</sub>		46		nC	V <sub>DS</sub> = 800 V, V <sub>GS</sub> = -5 V/20 V I <sub>DS</sub> = 50 A
Gate to Drain Charge	Q <sub>gd</sub>		50			
Total Gate Charge	Q <sub>g</sub>		161			

**Reverse Diode Characteristics (T<sub>VJ</sub> = 25 °C)**

Characteristics	Symbol	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage	V <sub>SD</sub>	4.1		V	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 25 A
		3.7		V	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 25 A, T <sub>VJ</sub> = 175 °C
Reverse Recovery Time	t <sub>rr</sub>	45		ns	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 50 A, V <sub>R</sub> = 800 V dif/dt = 1000 A/μs, T <sub>VJ</sub> = 175 °C
Reverse Recovery Charge	Q <sub>rr</sub>	406		nC	
Peak Reverse Recovery Current	I <sub>rrm</sub>	13.5		A	

### Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

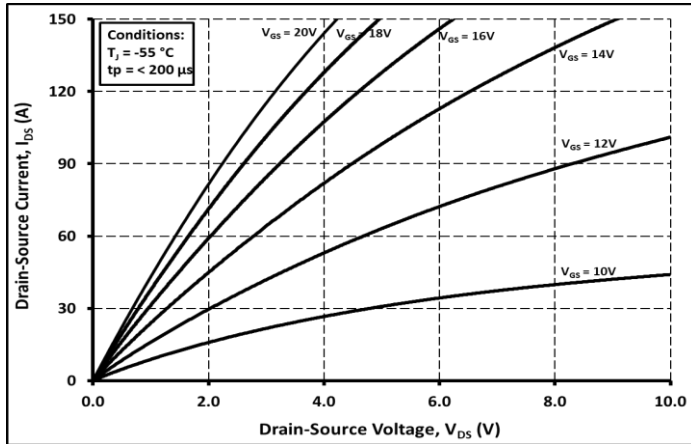


Figure 1.

Output Characteristics  $T_{vj} = -55\text{ }^{\circ}\text{C}$

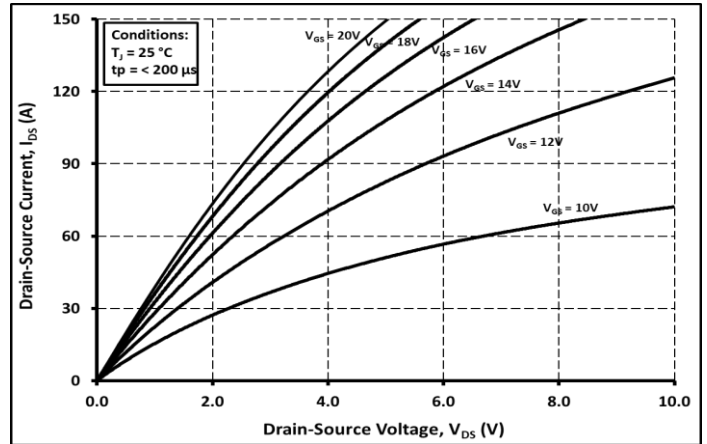


Figure 2.

Output Characteristics  $T_{vj} = 25\text{ }^{\circ}\text{C}$

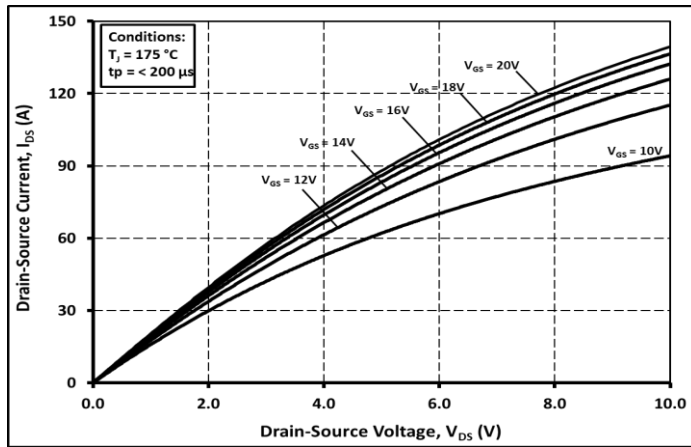


Figure 3.

Output Characteristics  $T_{vj} = 175\text{ }^{\circ}\text{C}$

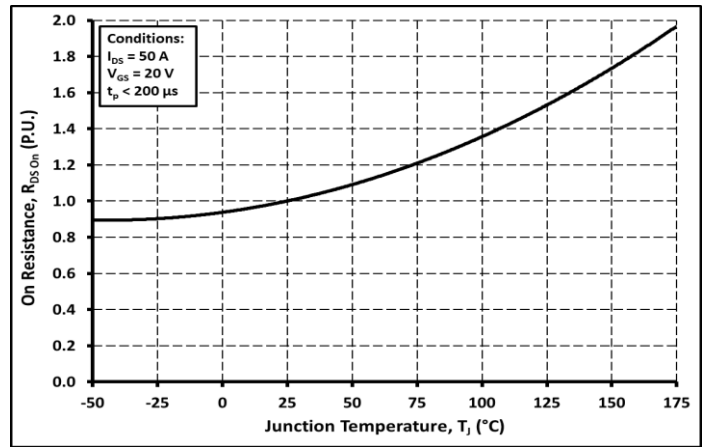


Figure 4.

Normalized On-Resistance vs. Temperature

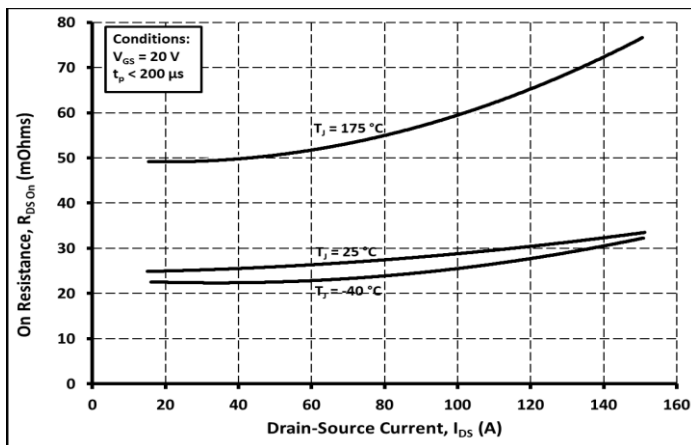


Figure 5.

On-Resistance vs. Drain Current For Various Temperatures

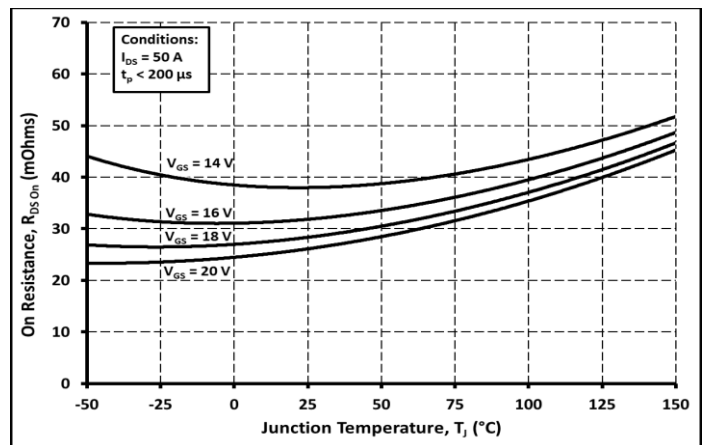


Figure 6.

On-Resistance vs. Temperature For Various Gate Voltages



### Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

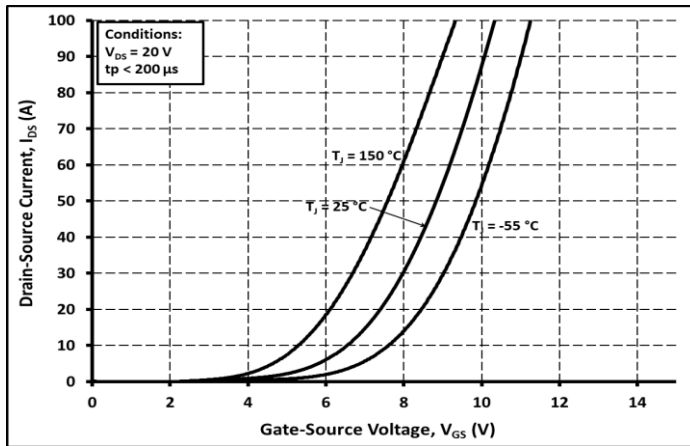


Figure 7.

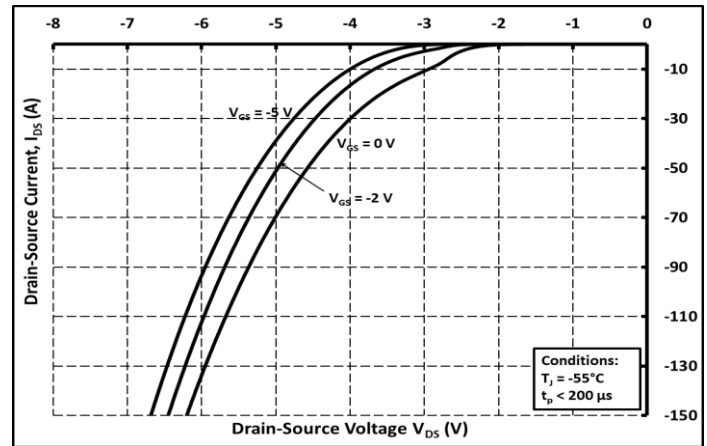


Figure 8.

Transfer Characteristic For Various Junction Temperatures

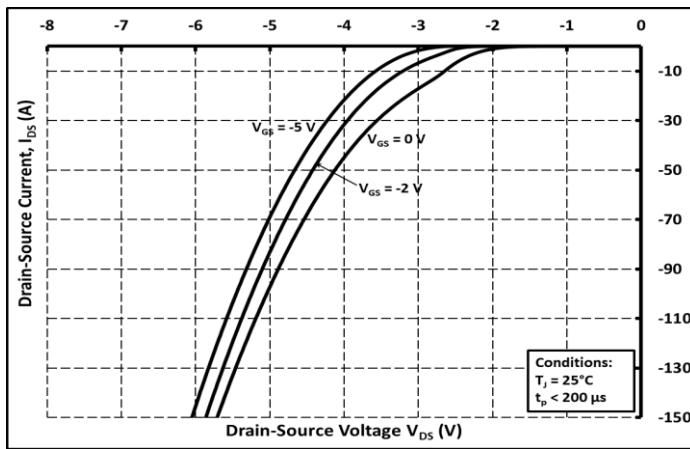


Figure 9.

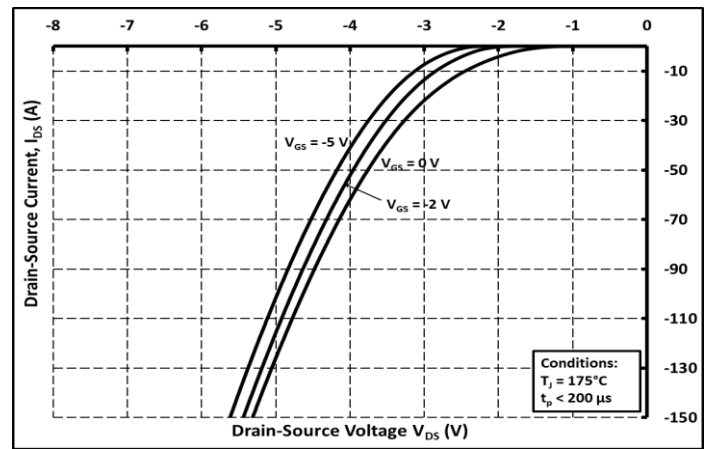


Figure 10.

Body Diode Characteristic at  $T_{vj} = 25\text{ }^{\circ}\text{C}$

Body Diode Characteristic at  $T_{vj} = 175\text{ }^{\circ}\text{C}$

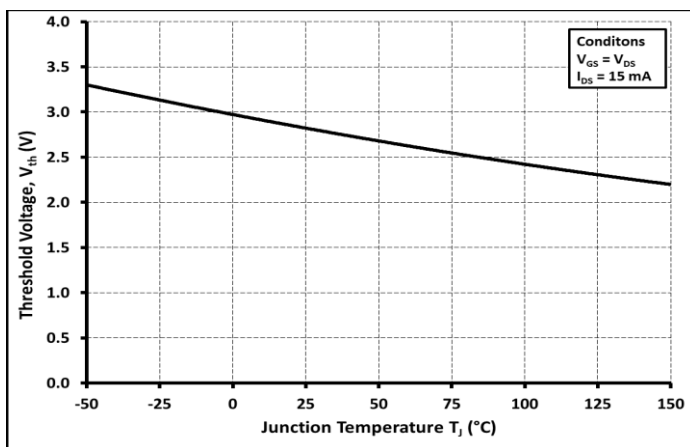


Figure 11.

Threshold Voltage vs. Temperature

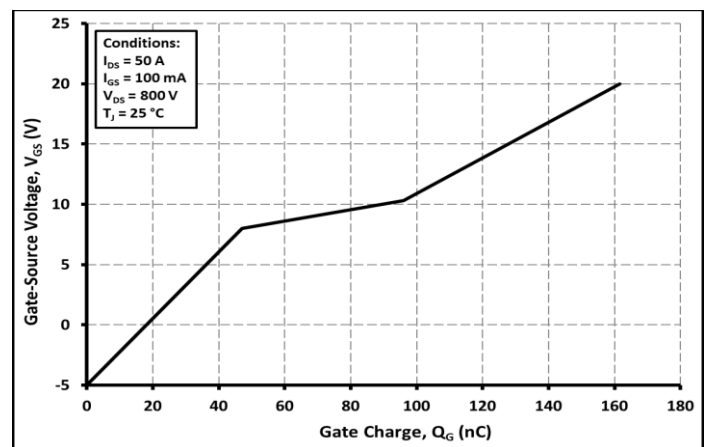


Figure 12.

Gate Charge Characteristics



### Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

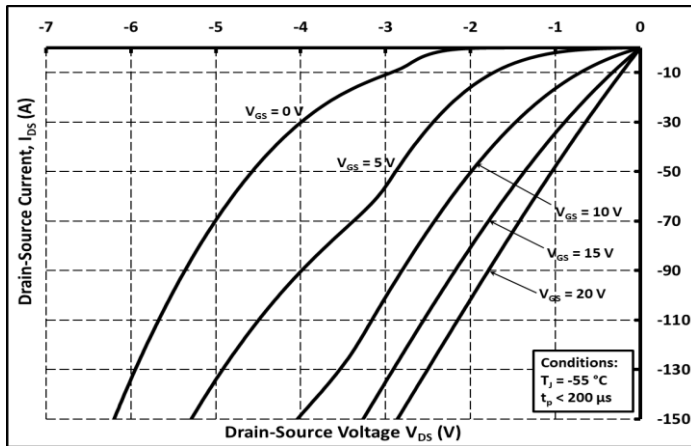


Figure 13.

3rd Quadrant Characteristic at  $T_{vj} = -55\text{ }^{\circ}\text{C}$

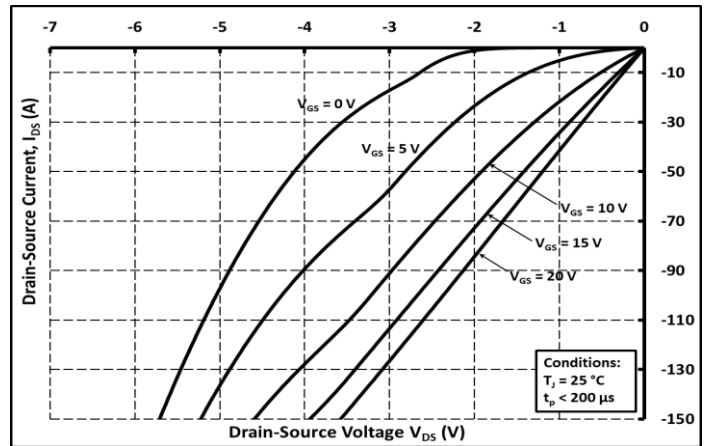


Figure 14.

3rd Quadrant Characteristic at  $T_{vj} = 25\text{ }^{\circ}\text{C}$

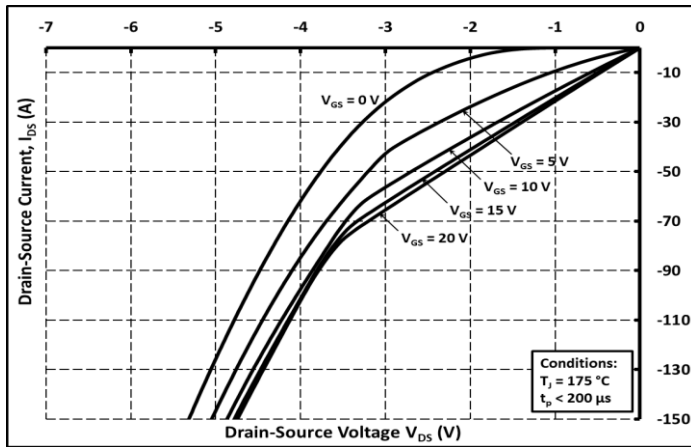


Figure 15.

3rd Quadrant Characteristic at  $T_{vj} = 175\text{ }^{\circ}\text{C}$

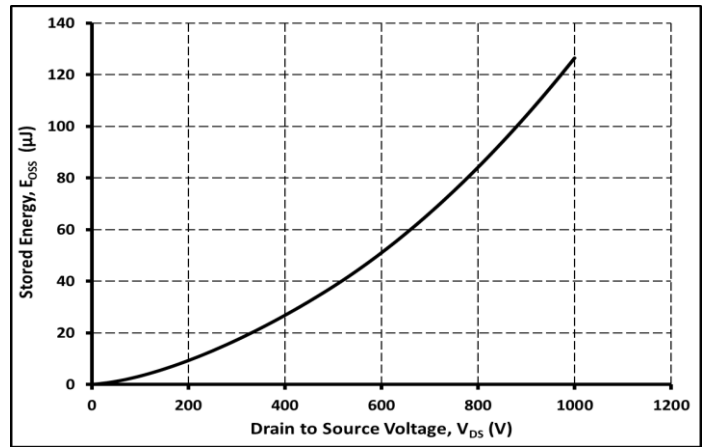


Figure 16.

Output Capacitor Stored Energy

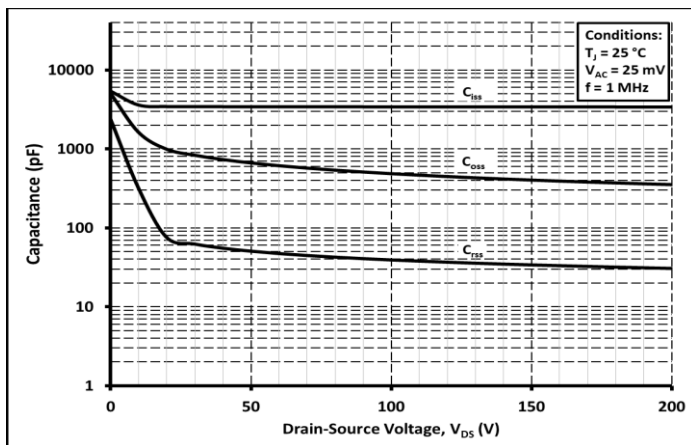


Figure 17.

Capacitances vs. Drain-Source Voltage (0-200V)

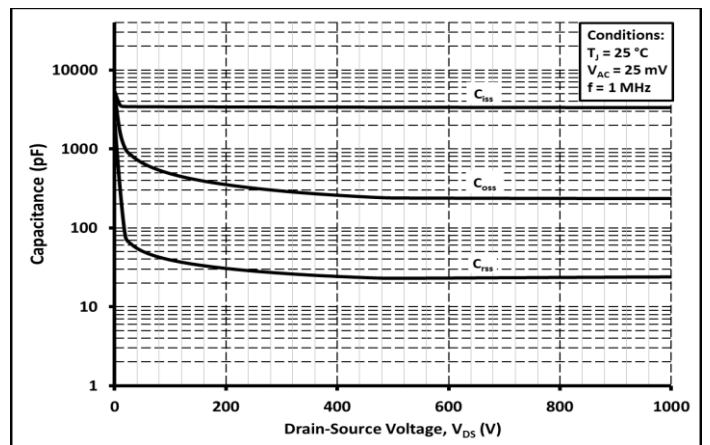
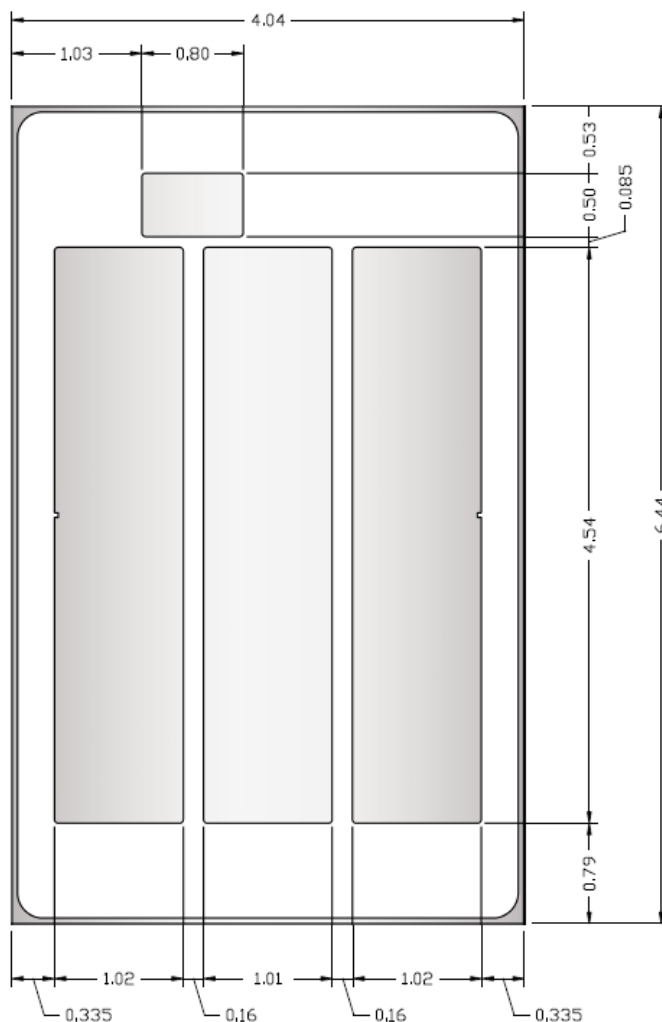


Figure 18.

Capacitances vs. Drain-Source Voltage (0-1200V)



## Product Dimensions CPM2-1200-0025A



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Parameter	Typical	Units
Die Size (L x W)	4.04 x 6.44	mm
Exposed Source Pad Metal Dimensions	1.0 x 4.54 (x3)	mm
Gate Pad Dimensions	0.50 x 0.80	mm
Chip Thickness <sup>1</sup>	180 ± 40	μm
Frontside (Source) metalization (Al)	4	μm
Frontside (Gate) metalization (Al)	4	μm
Backside (Drain) metalization (Ni/Au)	0.8 / 0.1	μm

<sup>1</sup> SiC wafer thickness



### Product Ordering Information

Order Number	Description	Package
CPM2-1200-0025A-FY6	SiC MOSFET G2 IND 1200V/25mO UV MLT	Bare Die Product

### Revision History

Revision History	Date of Change	Brief Summary
0		Initial Release
1	12/21/2023	<ul style="list-style-type: none"> <li>• Template updated</li> </ul>



## Notes & Disclaimer

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